

捷多邦专业PCB打样工厂 24小时机  
急出货

# TN2010L, TN2410L

## N-Channel Enhancement-Mode MOS Transistors

T·35-25

### PRODUCT SUMMARY

PART NUMBER	V <sub>(BR)DSS</sub> (V)	r <sub>DSON</sub> (Ω)	I <sub>D</sub> (A)
TN2010L	200	10	0.18
TN2410L	240	10	0.18

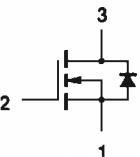
TO-92 (TO-226AA)



BOTTOM VIEW



1 SOURCE  
2 GATE  
3 DRAIN



Performance Curves: VNDB24

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS		UNITS
		TN2010L	TN2410L	
Drain-Source Voltage	V <sub>DS</sub>	200	240	V
Gate-Source Voltage	V <sub>GS</sub>	±20	±20	
Continuous Drain Current	I <sub>D</sub>	±0.18	±0.18	A
		±0.11	±0.11	
Pulsed Drain Current <sup>1</sup>	I <sub>DM</sub>	±1	±1	
Maximum Power Dissipation	P <sub>D</sub>	0.8	0.8	W
		0.32	0.32	
Operating Junction & Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C
Lead Temperature (1/16" from case for 10 sec.)	T <sub>L</sub>	300		

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	LIMITS	UNITS
Junction-to-Ambient	R <sub>thJA</sub>	156	K/W

<sup>1</sup>Pulse width limited by maximum junction temperature.

**TN2010L, TN2410L**
 Siliconix  
incorporated

SPECIFICATIONS*				LIMITS			
PARAMETER	SYMBOL	TEST CONDITIONS		TYPE	MIN	MAX	UNIT
<b>STATIC</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}$ $I_D = 100 \mu\text{A}$	TN2410L	260	240		V
			TN2010L	240	200		
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 1 \text{ mA}$		1.4	0.5	1.8	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		$\pm 1$		$\pm 10$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 0.8 \times \text{rated } V_{(BR)DSS}, V_{GS} = 0 \text{ V}$		0.01		1	$\mu\text{A}$
			$T_J = 125^\circ\text{C}$	1.0		100	
On-State Drain Current <sup>c</sup>	$I_{D(\text{ON})}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$		0.8	0.25		A
Drain-Source On-Resistance <sup>c</sup>	$r_{DS(\text{ON})}$	$V_{GS} = 3.5 \text{ V}, I_D = 50 \text{ mA}$		6		15	$\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$		5		10	
		$T_J = 125^\circ\text{C}$		10		20	
Forward Transconductance <sup>c</sup>	$g_{FS}$	$V_{DS} = 10 \text{ V}, I_D = 0.2 \text{ A}$		500	100		mS
<b>DYNAMIC</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		110		135	pF
Output Capacitance	$C_{oss}$			30		50	
Reverse Transfer Capacitance	$C_{rss}$			5		20	
<b>SWITCHING</b>							
Turn-On Time	$t_{ON}$	$V_{DD} = 60 \text{ V}, R_L = 150 \Omega, I_D = 0.4 \text{ A}$ $V_{GEN} = 10 \text{ V}, R_G = 25 \Omega$ (Switching time is essentially independent of operating temperature)		15		35	ns
Turn-Off Time	$t_{OFF}$			30		60	

## NOTES:

- a.  $T_A = 25^\circ\text{C}$  unless otherwise noted.
- b. For design aid only, not subject to production testing.
- c. Pulse test: Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .